MDD10N074RH

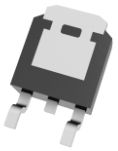
Single N-channel Trench MOSFET 100V 7.8mΩ 60A

FEATURES

- **Trench power MOSFET technology**
- **Very low on-resistance $R_{DS(on)}$**
- **100% Avalanche / Rg Tested**

Top View

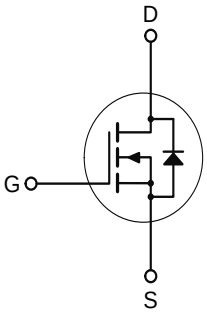
TO252



Bottom View

APPLICATIONS

- **Specifically for Syncronous Rectification**
- **Switching Applications**



KEY PERFORMANCE PARAMETERS

V_{DS}	**100**	V
$R_{DS(on),\ typ.}$	**0.0068**	Ω
I_D	**60**	A
Q_G	**72**	nC
Junction temperature, max	**150**	°C

RoHS Compliant
HALOGEN-FREE

ORDERING INFORMATION

Type / Ordering Code	Package	Marking	Packing	RoHS Status
MDD10N074RH	TO252	MDD10N074	Tape & Reel	Halogen Free

http://www.magnachip.com

ABSOLUTE MAXIMUM RATINGS, at T_C = 25°C, unless otherwise specified

PARAMETER		SYMBOL	RATING	UNIT
Drain-source Voltage		V_{DS}	100	V
Gate-source Voltage		V_{GS}	± 20	V
Drain current	Tc=25°C Silicon Limited	I_D	77	A
	Tc=25°C Package Limited		60	A
	Tc=100°C Silicon Limited		49	A
1) Pulsed drain current	Tc=25°C	I_{DM}	240	A
Total power dissipation	Tc=25°C	P_{tot}	96	W
	Tc=100°C		38	W
2) Avalanche energy, single pulse		E_{AS}	113	mJ
Operating and storage temperature		T_j, T_{stg}	- 55 ~ 150	°C

THERMAL CHARACTERISTICS

PARAMETER	SYMBOL	RATING	UNIT
Thermal resistance, junction - case	$R_{\theta JC}$	1.3	°C/W
3) Thermal resistance, junction - ambient	$R_{\theta JA}$	40	°C/W

ELECTRICAL CHARACTERISTICS (T_J = 25°C)

STATIC CHARACTERISTICS

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS / NOTE
Drain-source breakdown voltage	$V_{(BR)DSS}$	100	-	-	V	V_{GS}=0 V, I_D=250 μA
Gate threshold voltage	$V_{GS(th)}$	1.2	1.6	2.2	V	V_{DS}=V_{GS}, I_D=250 μA
Zero gate voltage drain current	I_{DSS}	-	-	1	μA	V_{DS}=100 V, V_{GS}=0 V
Gate-source leakage current	I_{GSS}	-	-	± 100	nA	V_{GS}=±20 V, V_{DS}=0 V
Drain-source on-state resistance	$R_{DS(on)}$	-	6.8	7.8	mΩ	V_{GS}=10 V, I_D=20 A
		-	7.9	9.4	mΩ	V_{GS}=4.5 V, I_D=15 A
4) Gate resistance	R_G		2.1		Ω	f=1MHz
4) Transconductance	g_{fs}	-	92	-	S	V_{DS}=10 V, I_D=20 A

4) DYNAMIC CHARACTERISTICS

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS / NOTE
Input capacitance	C_{iss}	-	4396	-	pF	V_{GS}=0 V, V_{DS}=40 V, f=1 MHz
Output capacitance	C_{oss}	-	511	-	pF	V_{GS}=0 V, V_{DS}=40 V, f=1 MHz
Reverse transfer capacitance	C_{rss}	-	30	-	pF	V_{GS}=0 V, V_{DS}=40 V, f=1 MHz
Turn-on delay time	$t_{d(on)}$	-	18.0	-	ns	V_{DD}=50 V, V_{GS}=10 V, I_D=20 A, R_G,ext=3Ω
Rise time	t_r	-	7	-	ns	V_{DD}=50 V, V_{GS}=10 V, I_D=20 A, R_G,ext=3Ω
Turn-off delay time	$t_{d(off)}$	-	88	-	ns	V_{DD}=50 V, V_{GS}=10 V, ID=20 A, $R_{G,ext}$=3Ω
Fall time	t_f	-	21.0	-	ns	V_{DD}=50 V, V_{GS}=10 V, I_D=20 A, R_G,ext=3Ω

4) GATE CHARGE CHARACTERISTICS

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS / NOTE
Gate to source charge	Q_{gs}	-	11	-	nC	V_{DD}=50 V, I_D=20 A, V_{GS}=0 to 10 V
Gate to drain charge	Q_{gd}	-	14	-	nC	V_{DD}=50 V, I_D=20 A, V_{GS}=0 to 10 V
Gate charge total	Q_g	-	72	-	nC	V_{DD}=50 V, I_D=20 A, V_{GS}=0 to 10 V

SOURCE-DRAIN DIODE

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS / NOTE
4) Diode continous forward current	I_S	-	-	60	A	-
4) Diode pulse current	$I_{S,pulse}$	-	-	240	A	pulsed; tp ≤ 10 μs
Diode forward voltage	V_{SD}	-	0.8	1.2	V	V_{GS}=0 V, I_S=20 A
4) Reverse recovery time	t_{rr}	-	69	-	ns	I_F=20 A, d_{iF}/dt=100 A/μs
4) Reverse recovery charge	Q_{rr}	-	143	-	nC	I_F=20 A, d_{iF}/dt=100 A/μs

Notes

1. Pulse width limited by Tjmax
2. starting Tj = 25℃, L = 1.0mH, IAS = 15A, VDD = 50V, VGS = 10V
3. Surface mounted FR-4 board by JEDEC (jesd51-7)
4. The parameter is not subject to production testing - guaranteed by design.

ELECTRICAL CHARACTERISTICS DIAGRAMS (25 ℃, unless otherwise noted)

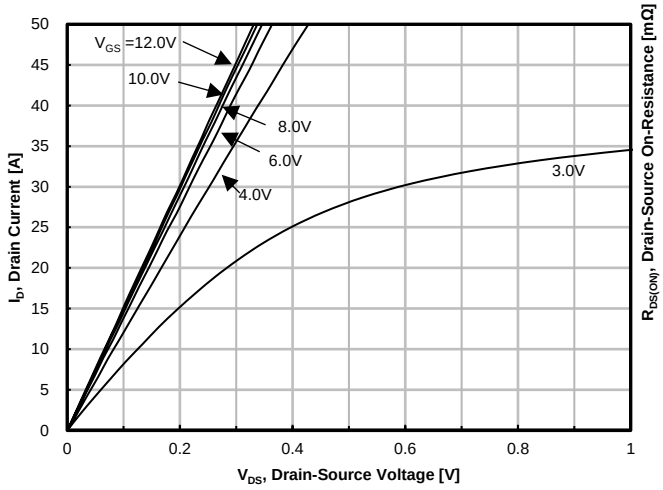


Fig. 1. On-Region Characteristics

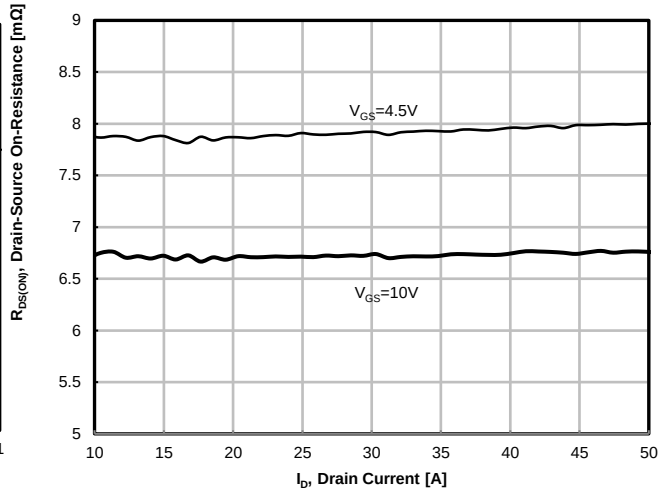


Fig. 2. On-Resistance vs. Drain Current and Gate Voltage

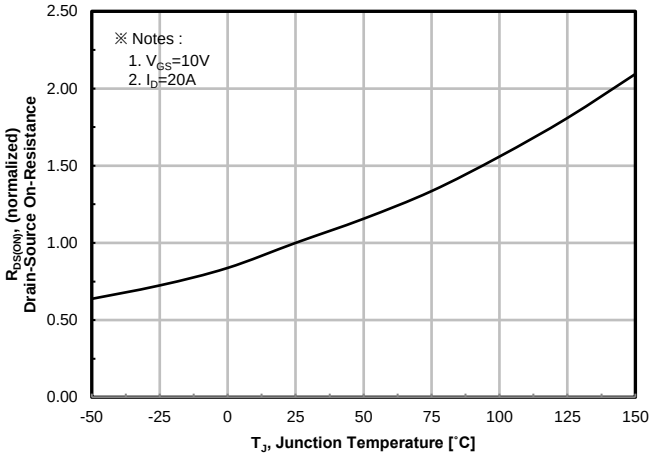


Fig. 3. On-Resistance vs. Junction Temperature

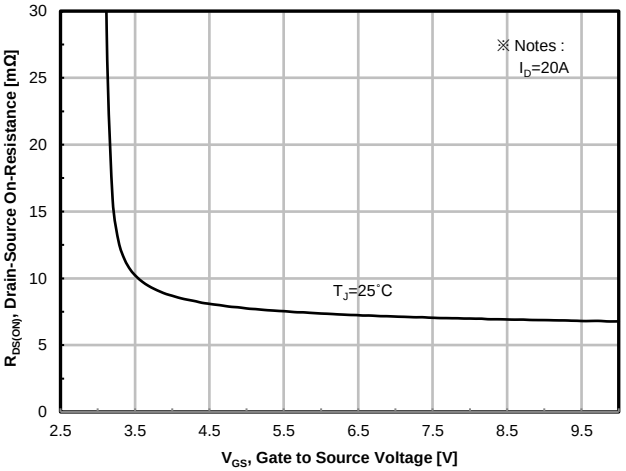


Fig. 4. On-Resistance vs. Gate to Source Voltage

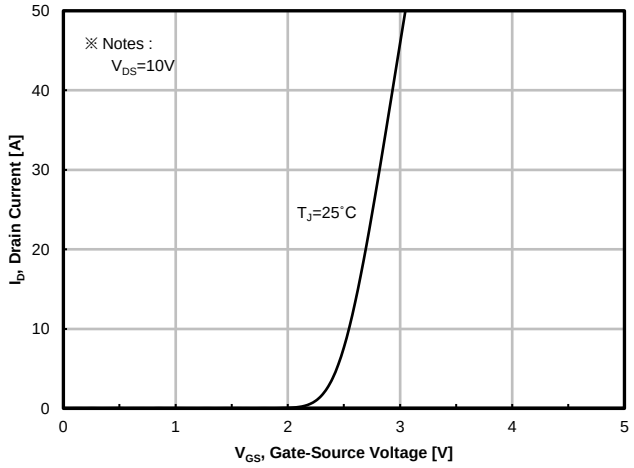


Fig. 5. Transfer Characteristics

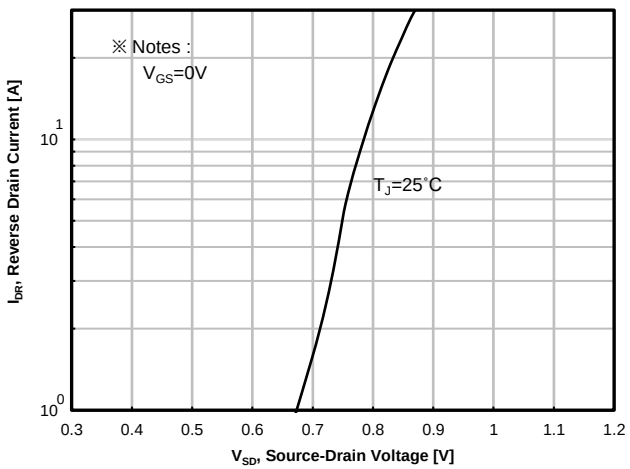


Fig. 6. Source-Drain Diode Forward Voltage

ELECTRICAL CHARACTERISTICS DIAGRAMS (25 ℃, unless otherwise noted)

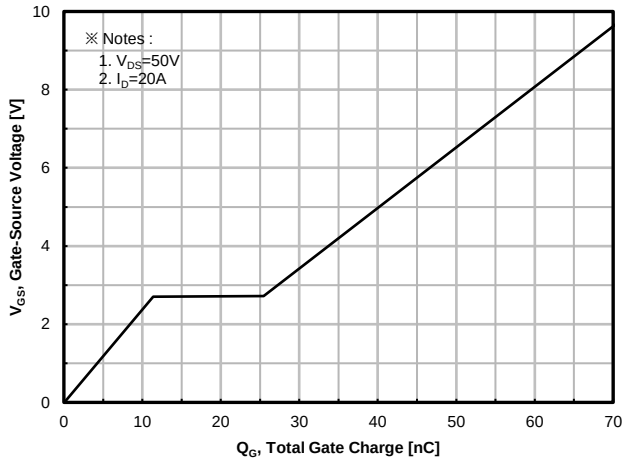


Fig. 7. Gate Charge

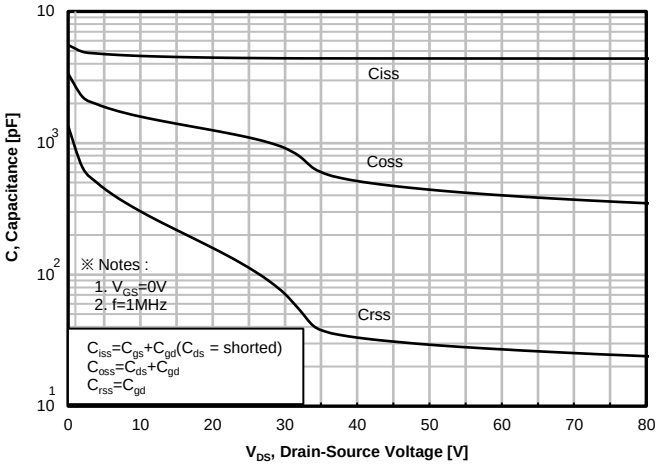


Fig. 8. Capacitance

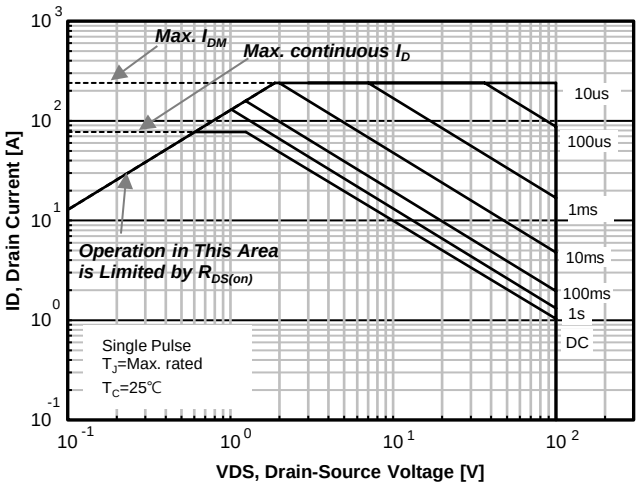


Fig. 9. Safe Operating Area

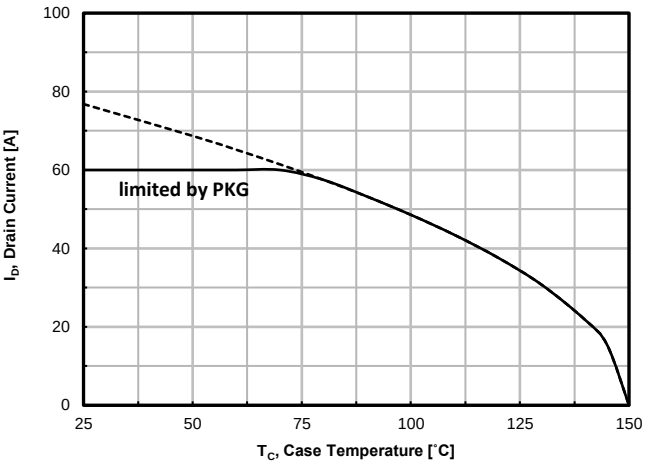


Fig. 10. Maximum Drain Current vs. Case Temperature

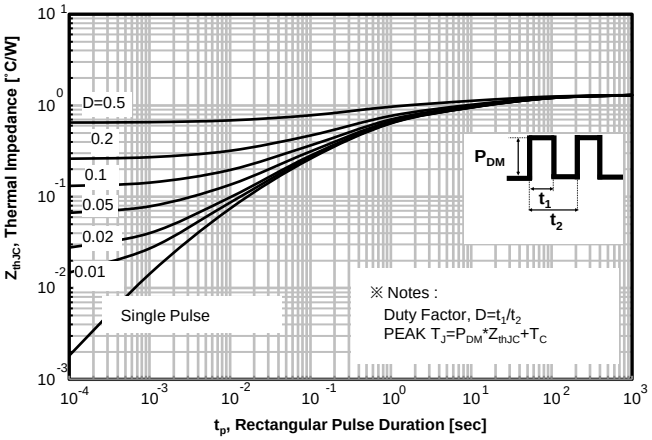
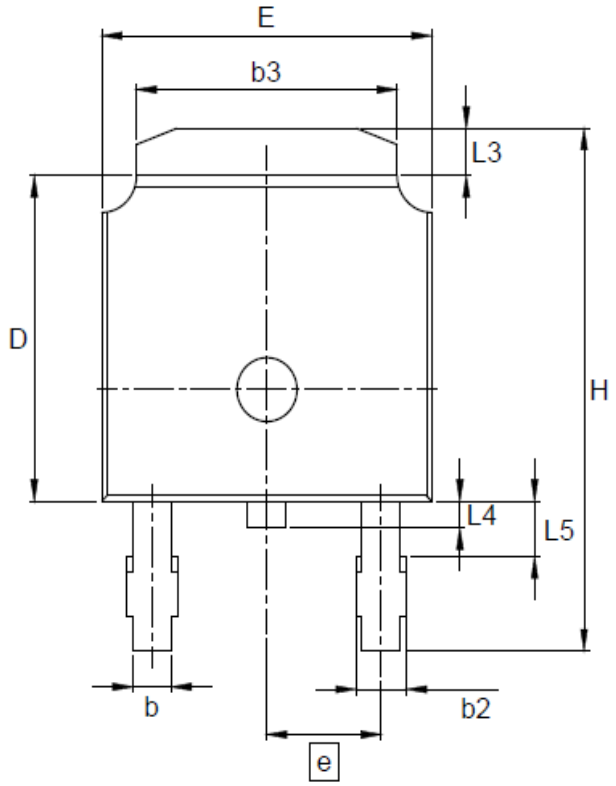
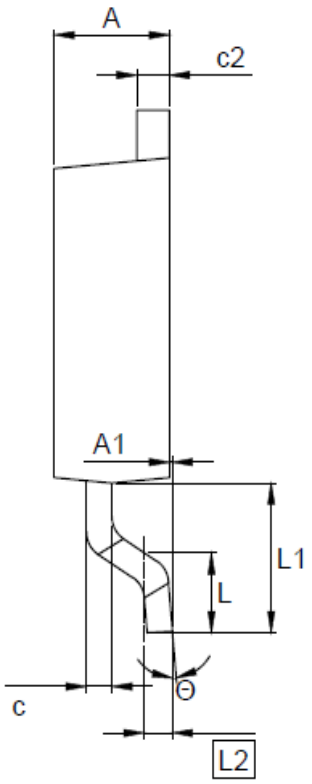


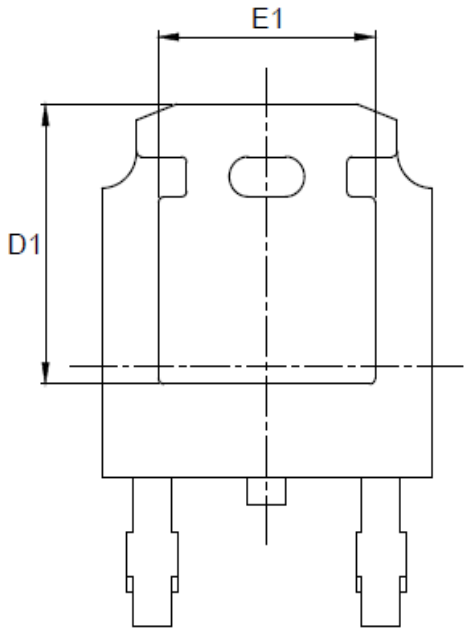
Fig. 11. Thermal Transient Impedance, Junction-to-Ambient

Package information

TO252







Symbol	Dimension (mm)		
	Min	Nom	Max
E	6.35	–	6.73
L	1.40	1.52	1.78
L1		2.74 REF	
L2		0.508 BSC	
L3	0.89	–	1.27
L4	–	–	1.02
L5	–	–	1.52
D	5.97	6.10	6.22
H	9.40	–	10.41
b	0.64	–	0.89
b2	0.76	–	1.14
b3	4.95	–	5.46
e		2.286 BSC	
A	2.18	–	2.39
A1	–	–	0.13
c	0.46	–	0.61
c2	0.46	–	0.89
D1	5.21	–	–
E1	4.32	–	–
Θ	0°	–	10°

Notes :

1. Package body size , length and width do not includes mold flash, protrusions and gate burrs.

DISCLAIMER :

The Products are not designed for use in hostile environments, including, without limitation, aircraft, nuclear power generation, medical appliances, and devices or systems in which malfunction of any Product can reasonably be expected to result in a personal injury. Seller's customers using or selling Seller's products for use in such applications do so at their own risk and agree to fully defend and indemnify Seller.